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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	38
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd20g15b-aut

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### 1. Description

The Atmel® | SMART™ SAM D20 is a series of low-power microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, and ranging from 32- to 64-pins with up to 256KB Flash and 32KB of SRAM. The SAM D20 devices operate at a maximum frequency of 48MHz and reach 2.46 CoreMark/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Atmel Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The SAM D20 devices provide the following features: In-system programmable Flash, eight-channel Event System, programmable interrupt controller, up to 52 programmable I/O pins, 32-bit real-time clock and calendar, up to eight 16-bit Timer/Counters (TC) . The timer/counters can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC. The series provide up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I<sup>2</sup>C up to 400kHz, up to twenty-channel 350ksps 12-bit ADC with programmable gain and optional oversampling and decimation supporting up to 16-bit resolution, one 10-bit 350ksps DAC, two analog comparators with window mode, Peripheral Touch Controller supporting up to 256 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

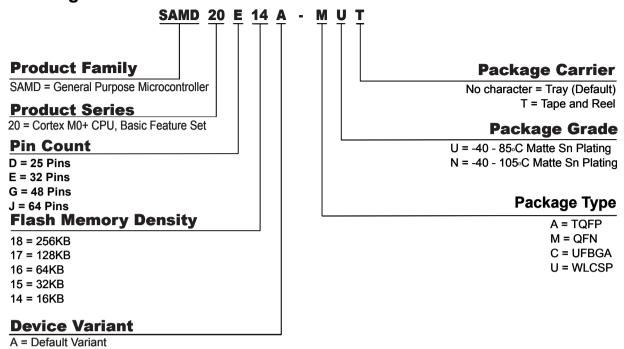
The SAM D20 devices have two software-selectable sleep modes, idle and standby. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped expect those selected to continue running. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for non-intrusive on-chip debug of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

The SAM D20 devices are supported with a full suite of program and system development tools, including C compilers, macro assemblers, program debugger/simulators, programmers and evaluation kits.



# 3. Ordering Information



#### 3.1. SAM D20E

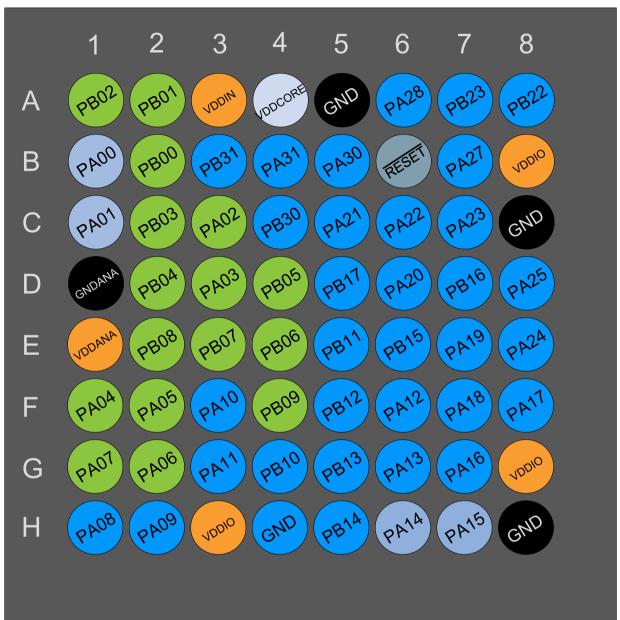
Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20E14A-AU	16K	2K	TQFP32	Tray
ATSAMD20E14A-AUT				Tape & Reel
ATSAMD20E14A-AN				Tray
ATSAMD20E14A-ANT				Tape & Reel
ATSAMD20E14A-MU			QFN32	Tray
ATSAMD20E14A-MUT				Tape & Reel
ATSAMD20E14A-MN				Tray
ATSAMD20E14A-MNT				Tape & Reel



Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20E15A-AU	32K 4K		TQFP32	Tray
ATSAMD20E15A-AUT		Tape & Reel		
ATSAMD20E15A-AN				Tray
ATSAMD20E15A-ANT				Tape & Reel
ATSAMD20E15A-MU			QFN32	Tray
ATSAMD20E15A-MUT				Tape & Reel
ATSAMD20E15A-MN				Tray
ATSAMD20E15A-MNT				Tape & Reel
ATSAMD20E16A-AU	64K	8K	TQFP32	Tray
ATSAMD20E16A-AUT				Tape & Reel
ATSAMD20E16A-AN				Tray
ATSAMD20E16A-AFT				Tape & Reel
ATSAMD20E16A-MU			QFN32	Tray
ATSAMD20E16A-MUT				Tape & Reel
ATSAMD20E16A-MN				Tray
ATSAMD20E16A-MNT				Tape & Reel
ATSAMD20E17A-AU	128K	16K	TQFP32	Tray
ATSAMD20E17A-AUT				Tape & Reel
ATSAMD20E17A-AN				Tray
ATSAMD20E17A-ANT				Tape & Reel
ATSAMD20E17A-MU			QFN32	Tray
ATSAMD20E17A-MUT				Tape & Reel
ATSAMD20E17A-MN				Tray
ATSAMD20E17A-MNT				Tape & Reel
ATSAMD20E18A-AU	256K	32K	TQFP32	Tray
ATSAMD20E18A-AUT				Tape & Reel
ATSAMD20E18A-AN				Tray
ATSAMD20E18A-AFT				Tape & Reel
ATSAMD20E18A-MU			QFN32	Tray
ATSAMD20E18A-MUT				Tape & Reel
ATSAMD20E18A-MN				Tray
ATSAMD20E18A-MNT				Tape & Reel



#### 5.1.2. UFBGA64

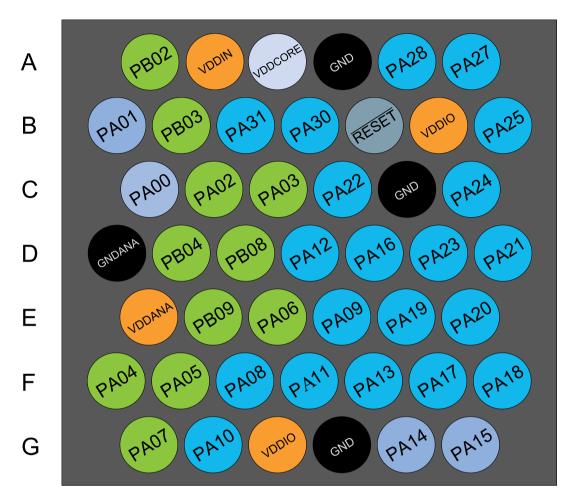


- DIGITAL PIN
- ANALOG PIN
- OSCILLATOR
- GROUND
- INPUT SUPPLY
- REGULATED OUTPUT SUPPLY
- RESET PIN



#### 5.2.2. WLCSP45

12 10 8 6 4 2 13 11 9 7 5 3 1

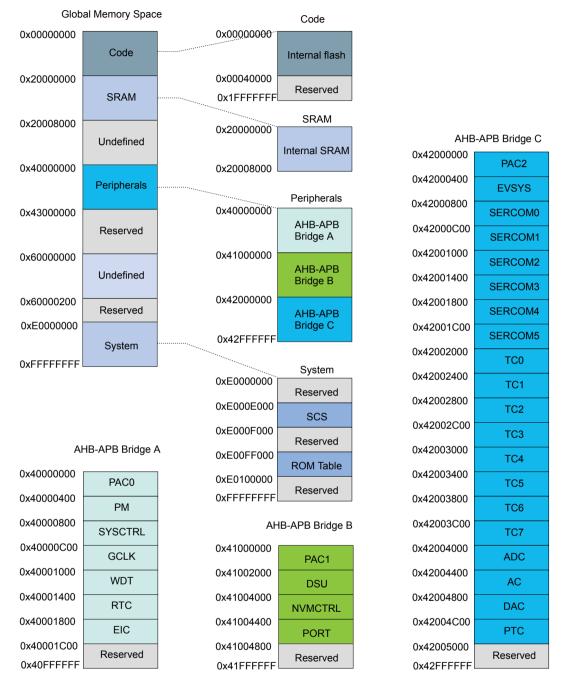


- DIGITAL PIN
- ANALOG PIN
- OSCILLATOR
- GROUND
- INPUT SUPPLY
- REGULATED OUTPUT SUPPLY
- RESET PIN



### 6. Product Mapping

Figure 6-1. Product Mapping



This figure represents the full configuration of the SAM D20 device with maximum flash and SRAM capabilities and a full set of peripherals. Refer to the Configuration Summary for details.



### 7. Processor And Architecture

### 7.1. Cortex M0+ Processor

The SAM D20 implements the ARM® Cortex®-M0+ processor, based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 core, and upward compatible to Cortex-M3 and M4 cores. The ARM Cortex-M0+ implemented is revision r0p1. For more information refer to http://www.arm.com.

#### 7.1.1. Cortex M0+ Configuration

Table 7-1. Cortex M0+ Configuration

Features	Configurable option	Device configuration
Interrupts	External interrupts 0-32	28
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Absent <sup>(1)</sup>
Memory Protection Unit	Not present or 8-region	Not present
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

#### Note:

1. All software run in privileged mode only.

The ARM Cortex-M0+ core has two bus interfaces:

- Single 32-bit AMBA-3 AHB-Lite system interface that provides connections to peripherals and all system memory, which includes flash and RAM.
- Single 32-bit I/O port bus interfacing to the PORT with 1-cycle loads and stores.

#### 7.1.2. Cortex-M0+ Peripherals

- System Control Space (SCS)
  - The processor provides debug through registers in the SCS. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- System Timer (SysTick)



- The System Timer is a 24-bit timer that extends the functionality of both the processor and the NVIC. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- Nested Vectored Interrupt Controller (NVIC)
  - External interrupt signals connect to the NVIC, and the NVIC prioritizes the interrupts.
     Software can set the priority of each interrupt. The NVIC and the Cortex-M0+ processor core are closely coupled, providing low latency interrupt processing and efficient processing of late arriving interrupts. Refer to Nested Vector Interrupt Controller and the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- System Control Block (SCB)
  - The System Control Block provides system implementation information, and system control.
     This includes configuration, control, and reporting of the system exceptions. Refer to the Cortex-M0+ Devices Generic User Guide for details (www.arm.com).
- Micro Trace Buffer (MTB)
  - The CoreSight MTB-M0+ (MTB) provides a simple execution trace capability to the Cortex-M0+ processor. Refer to section Micro Trace Buffer and the CoreSight MTB-M0+ Technical Reference Manual for details (www.arm.com).

#### 7.1.3. Cortex-M0+ Address Map

Table 7-2. Cortex-M0+ Address Map

Address	Peripheral
0xE000E000	System Control Space (SCS)
0xE000E010	System Timer (SysTick)
0xE000E100	Nested Vectored Interrupt Controller (NVIC)
0xE000ED00	System Control Block (SCB)
0x41006000 (see also Product Mapping)	Micro Trace Buffer (MTB)

#### 7.1.4. I/O Interface

#### 7.1.4.1. Overview

Because accesses to the AMBA® AHB-Lite<sup>™</sup> and the single cycle I/O interface can be made concurrently, the Cortex-M0+ processor can fetch the next instructions while accessing the I/Os. This enables single cycle I/O accesses to be sustained for as long as needed. Refer to *CPU Local Bus* for more information.

#### 7.1.4.2. Description

Direct access to PORT registers.

### 7.2. Nested Vector Interrupt Controller

#### 7.2.1. Overview

The Nested Vectored Interrupt Controller (NVIC) in the SAM D20 supports 32 interrupt lines with four different priority levels. For more details, refer to the Cortex-M0+ Technical Reference Manual (www.arm.com).

#### 7.2.2. Interrupt Line Mapping

Each of the 28 interrupt lines is connected to one peripheral instance, as shown in the table below. Each peripheral can have one or more interrupt flags, located in the peripheral's Interrupt Flag Status and Clear



Peripheral Source	NVIC Line
DAC – Digital-to-Analog Converter	23
PTC – Peripheral Touch Controller	24

#### 7.3. Micro Trace Buffer

#### 7.3.1. Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

#### 7.3.2. Overview

When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits.
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.



Write-protect registers allow the user to disable a selected peripheral's write-protection without doing a read-modify-write operation. These registers are mapped into two I/O memory locations, one for clearing and one for setting the register bits. Writing a one to a bit in the Write Protect Clear register (WPCLR) will clear the corresponding bit in both registers (WPCLR and WPSET) and disable the write-protection for the corresponding peripheral, while writing a one to a bit in the Write Protect Set (WPSET) register will set the corresponding bit in both registers (WPCLR and WPSET) and enable the write-protection for the corresponding peripheral. Both registers (WPCLR and WPSET) will return the same value when read.

If a peripheral is write-protected, and if a write access is performed, data will not be written, and the peripheral will return an access error (CPU exception).

The PAC also offers a safety feature for correct program execution, with a CPU exception generated on double write-protection or double unprotection of a peripheral. If a peripheral n is write-protected and a write to one in WPSET[n] is detected, the PAC returns an error. This can be used to ensure that the application follows the intended program flow by always following a write-protect with an unprotect, and vice versa. However, in applications where a write-protected peripheral is used in several contexts, e.g., interrupts, care should be taken so that either the interrupt can not happen while the main application or other interrupt levels manipulate the write-protection status, or when the interrupt handler needs to unprotect the peripheral, based on the current protection status, by reading WPSET.

### 7.7. Register Description

Atomic 8-, 16- and 32-bit accesses are supported. In addition, the 8-bit quarters and 16-bit halves of a 32-bit register, and the 8-bit halves of a 16-bit register can be accessed directly. Refer to the Product Mapping for PAC locations.

#### **Related Links**

**Product Mapping on page 19** 

#### 7.7.1. PAC0 Register Description



Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 3 - GCLK

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 2 - SYSCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 1 - PM

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### 7.7.2. PAC1 Register Description



#### 7.7.2.1. Write Protect Clear

Name: WPCLR
Offset: 0x00
Reset: 0x000002

Property: -

Bit	31	30	29	28	27	26	25	24
Access								·
Reset								
Bit	23	22	21	20	19	18	17	16
Access								
Reset								
Bit	15	14	13	12	11	10	9	8
Access								
Reset								
Bit	7	6	5	4	3	2	1	0
		MTB			PORT	NVMCTRL	DSU	
Access		R/W			R/W	R/W	R/W	
Reset		0			0	0	1	

#### Bit 6 - MTB

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description	
0	Write-protection is disabled.	
1	Write-protection is enabled.	

#### Bit 3 - PORT

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description	
0	Write-protection is disabled.	
1	Write-protection is enabled.	

#### Bit 2 - NVMCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.



Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 1 - DSU

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description	
0	Write-protection is disabled.	
1	Write-protection is enabled.	

### 7.7.3. PAC2 Register Description



1	Value Description	
	0	Write-protection is disabled.
	1	Write-protection is enabled.

#### Bit 16 - ADC

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description	
0	Write-protection is disabled.	
1	Write-protection is enabled.	

#### Bits 15,14,13,12,11,10,9,8 - TCx

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description	
0	Write-protection is disabled.	
1	Write-protection is enabled.	

#### Bits 7,6,5,4,3,2 - SERCOMx

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description	
0	Write-protection is disabled.	
1	Write-protection is enabled.	

#### Bit 1 - EVSYS

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

1	<b>V</b> alue	Description	
(	)	Write-protection is disabled.	
•	1	Write-protection is enabled.	



## 8. Packaging Information

#### 8.1. Thermal Considerations

#### **Related Links**

**Junction Temperature on page 39** 

#### 8.1.1. Thermal Resistance Data

The following table summarizes the thermal resistance data depending on the package.

**Table 8-1. Thermal Resistance Data** 

Package Type	$\theta_{JA}$	θ <sub>JC</sub>
32-pin TQFP	68.0°C/W	25.8°C/W
48-pin TQFP	78.8°C/W	12.3°C/W
64-pin TQFP	66.7°C/W	11.9°C/W
32-pin QFN	37.2°C/W	13.1°C/W
48-pin QFN	33.0°C/W	11.4°C/W
64-pin QFN	33.5°C/W	11.2°C/W
64-ball UFBGA	67.4°C/W	12.4°C/W
45-ball WLCSP	37.0°C/W	0.36°C/W

#### 8.1.2. Junction Temperature

The average chip-junction temperature, T<sub>J</sub>, in °C can be obtained from the following:

1. 
$$T_J = T_A + (P_D \times \theta_{JA})$$

2. 
$$T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$$

#### where:

- $\theta_{JA}$  = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- $\theta_{JC}$  = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- θ<sub>HEATSINK</sub> = Thermal resistance (°C/W) specification of the external cooling device
- P<sub>D</sub> = Device power consumption (W)
- T<sub>A</sub> = Ambient temperature (°C)

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T<sub>J</sub> in °C.

#### **Related Links**

Thermal Considerations on page 39



#### Table 8-5. Device and Package Maximum Weight

200	mg
	_

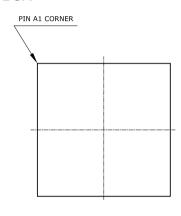
#### Table 8-6. Package Charateristics

М	oisture Sensitivity Level	MSL3
	,	

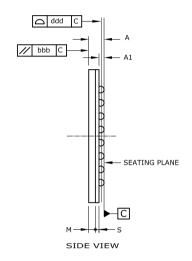
#### Table 8-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

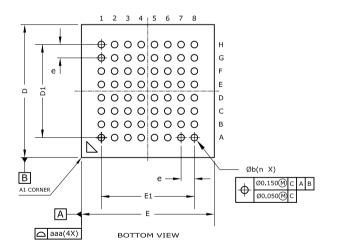
#### 8.2.3. 64-ball UFBGA



TOP VIEW







SYMBOL	MIN	МОИ	MAX	NOTE
Α			0.650	
A1	0.140		0.240	
E/D		5.00 / 5	5.00	
E1/D1		3.50 / 3	.50	
b	0.200		0.300	
е	Ball pitch : 0.500			
М	Mold thickness : 0.250 ref			
S	Subst thickness : 0.136 ref			
aaa	Pack edge tolerance : 0.100			
bbb	Mold flatness : 0.100			
ddd	Copla: 0.100			
ball diam	0.250			
n	64			

- Notes: 1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
  - 2. Array as seen from the bottom of the package.
  - 3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.

    4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

Table 8-8. Device and Package Maximum Weight

27.4 mg		
---------	--	--



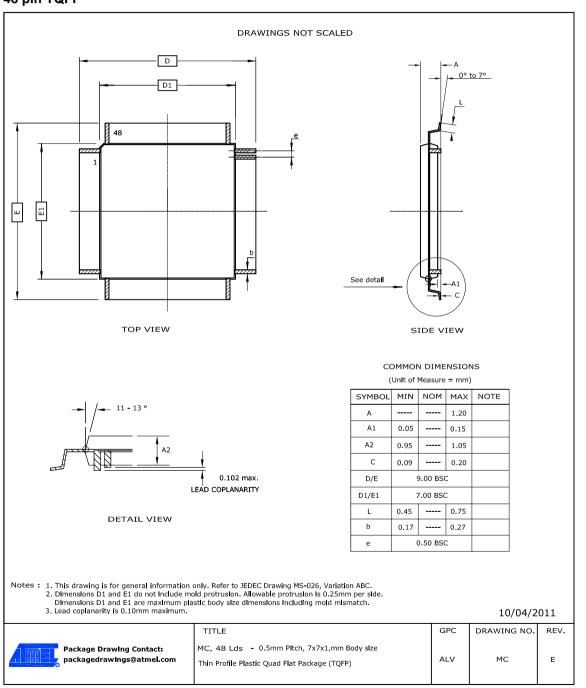
#### Table 8-9. Package Characteristics

Moisture Sensitivity Level	MSL3

#### Table 8-10. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E8

#### 8.2.4. 48 pin TQFP





### Table 8-11. Device and Package Maximum Weight

140	mg
1.10	9

#### **Table 8-12. Package Characteristics**

М	oisture Sensitivity Level	MSL3
	,	

#### Table 8-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3



#### Table 8-16. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

#### 8.2.6. 45-ball WLCSP

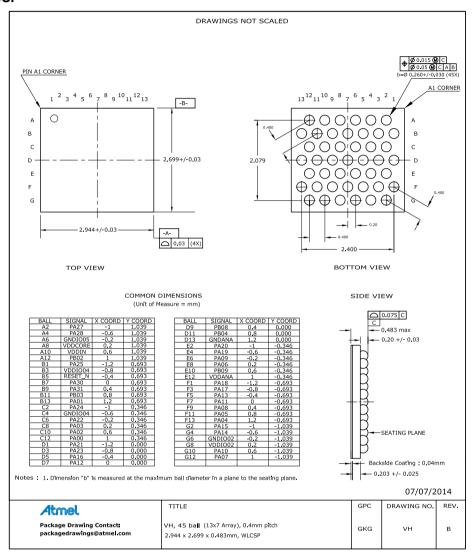


Table 8-17. Device and Package Maximum Weight

7.3	mg
	J 9

#### Table 8-18. Package Characteristics

Moisture Sensitivity Level	MSL1
----------------------------	------

#### Table 8-19. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

